INTEGRATED CIRCUITS



Product specification Replaces datasheet NE/SA5225 of 1997 Jun 05 IC19 Data Handbook

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SA5225

DESCRIPTION

The SA5225 is a high-gain limiting amplifier that is designed to process signals from fiber optic preamplifiers. Capable of operating at 125Mb/s, the chip has input signal level-detection with a user-adjustable threshold. The DATA and LEVEL-DETECT outputs are differential for optimum noise margin and ease of use. Also available is the SA5224 which is optimized for FDDI applications.

FEATURES

- Wideband operation: 1.0kHz to 120MHz typical
- Applicable in 155Mb/s OC3/SONET receivers
- Operation with single +5V or -5.2V supply
- Differential 10k ECL outputs
- Programmable input signal level-detection
- Fully differential for excellent PSRR to 1GHz

APPLICATIONS

- Data communication in noisy industrial environments
- LANs

ORDERING INFORMATION

DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG #	
16-Pin Plastic Small Outline (SO) Package	−40 to +85°C	SA5225D	SOT109-1	

PIN DESCRIPTION

CAZN 1

2

4

6

CAZP

GNDA 3

DIN

DIN 5

JAM [8

VCCA CF 7 D Package

Figure 1. Pin Configuration

16 VSET

15 VREF

14

13 DOUT

12

11 GNDE

10 ST

9 ST

SD00374

VCCE

DOUT

BLOCK DIAGRAM

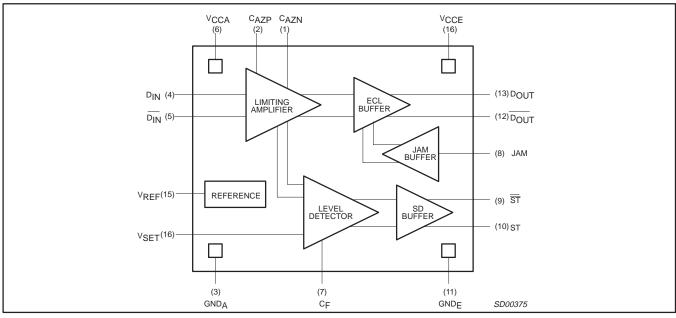


Figure 2. Block Diagram



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PIN DESCRIPTIONS

PIN NO.	NAME	FUNCTION
1	C _{AZN}	Auto-zero capacitor pin. Connecting a capacitor between this pin and C _{AZP} will cancel the offset voltage of the limiting amplifier.
2	C _{AZP}	Auto-zero capacitor pin. Connecting a capacitor between this pin and C _{AZN} will cancel the offset voltage of the limiting amplifier.
3	GND _A	Analog GND pin. Connect to ground for +5V upshifted ECL operation. Connect to –5.2V for standard ECL operation. Must be at same potential as GND _E (Pin 11).
4	D _{IN}	Differential input. DC bias level is set internally at approximately 2.9V. Complimentary to DIN (Pin 5).
5	D _{IN}	Differential input. DC bias level is set internally at approximately 2.9V. Complimentary to DIN (Pin 4).
6	V _{CCA} Analog power supply pin. Connect to a +5V supply for upshifted ECL operation. Connect to ground for standar ECL operation. Must be at same potential as V _{CCE} (Pin 14).	
7	C _F	Filter capacitor for level detector. Capacitor should be connected between this pin and V_{CCA} .
8	JAM	This ECL-compatible input controls the output buffers $\overline{D_{OUT}}$ and D_{OUT} (Pins 12 and 13). When an ECL LOW signal is applied, the outputs will follow the input signal. When an ECL HIGH signal is applied, the D_{OUT} and $\overline{D_{OUT}}$ pins will latch into LOW and HIGH states, respectively. When left unconnected, this pin is actively pulled-low (JAM OFF).
9	ST	Input signal level-detect STATUS. This ECL output is high when the input signal is below the user programmable threshold level.
10	ST	ECL compliment of ST (Pin 9).
11	GND _E	Digital GND pin. Connect to ground for $+5V$ upshifted ECL operation. Connect to a negative supply for normal ECL operation. Must be at the same potential as GND _A (Pin 3).
12	D _{OUT}	ECL-compatible output. Nominal level is V_{CCE} -1.3V. When JAM is HIGH, this pin will be forced into an ECL HIGH condition. Complimentary to D_{OUT} (Pin 13).
13	D _{OUT}	ECL-compatible output. Nominal level is V_{CCE} -1.3V. When JAM is HIGH, this pin will be forced into an ECL LOW condition. Complimentary to $\overline{D_{OUT}}$ (Pin 12).
14	V _{CCE}	Digital power supply pin. Connect to a +5V supply for upshifted ECL operation. Connect to ground during normal ECL operation. Must be at the same potential as V_{CCA} (Pin 6).
15	V _{REF}	Reference voltage for threshold level voltage divider. Nominal value is approximately 2.64V.
16	V _{SET}	Input threshold level setting circuit. This input can come from a voltage divider between V _{REF} and GND _A .

ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER	RATING	UNITS
V _{CC}	V _{CC} Power supply (V _{CC} - GND)		V
T _A	T _A Operating ambient		°C
TJ	T _J Operating junction		°C
T _{STG}	T _{STG} Storage		°C
PD	P _D Power dissipation, T _A = 25°C (still air) ¹ 16-pin Plastic SO		mW

NOTE:

1. Maximum dissipation is determined by the ambient temperature and the thermal resistance, θ_{JA} : 16-pin SO: $\theta_{JA} = 110^{\circ}$ C/W

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	RATING	UNITS
V _{CC}	Supply voltage	4.5 to 5.5	V
T _A	Ambient temperature ranges	-40 to +85	°C
T _J Junction temperature ranges		-40 to +110	°C

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DC ELECTRICAL CHARACTERISTICS

Min and Max limits apply over operating temperature at V_{CC} = 5V ±10%, unless otherwise specified. Typical data apply at T_A = 25°C and V_{CC} = +5V.

SYMBOL	DADAMETED	TEAT CONDITIONS	SA5225			T
	PARAMETER	TEST CONDITIONS	Min Typ Max		Мах	
V _{IN}	Input signal voltage single-ended differential		0.002 0.004		1.5 3.0	V _{P-P}
V _{OS}	Input offset voltage ²				50	μV
V _N	Input RMS noise ²				60	μV
V _{TH}	Input level-detect programmability single-en- ded	V _{IN} = 200kHz square wave	2		12	mV _{P-P}
V _{HYS}	Level-detect hysteresis ³		2	3	4	dB
I _{CC}	V _{CCA} + V _{CCE} supply current	No ECL loading		27	35	mA
I _{INL}	JAM input current	Pin 8 = 0V	-10		10	μA
V _{IH}	Minimum input for JAM = high ¹		-1.165			V _{DC}
V _{IL}	Maximum input for JAM = low ¹				-1.490	V _{DC}
V _{OH} ⁴	Status pins		-1.0		-0.81	V _{DC}
V _{OL} ⁴	Status pins		-1.95		-1.63	V _{DC}

NOTES:

1. These ECL specifications are referenced to the V_{CCE} rail and apply for $T_A = 0^{\circ}C$ to $85^{\circ}C$.

2. Guaranteed by design.

3. Also see the SA5224 which has 5dB \pm 1dB hysteresis for FDDI compatibility.

4. Valid for Status pins only (#9, 10).

Table 1. 10K ECL Voltage Levels (referenced to V_{CCE}) (Pins 12 & 13 only)

PARAMETER	−30°C	0°C	25°C	75°C	85°C	UNIT
V _{OHMAX}	-0.890	-0.840	-0.810	-0.735	-0.700	V _{DC}
V _{OHMIN}	-1.060	-1.020	-0.980	-0.920	-0.890	V _{DC}
V _{OLMAX}	-1.650	-1.630	-1.630	-1.600	-1.615	V _{DC}
V _{OLMIN}	-1.890	-1.950	-1.950	-1.950	-1.920	V _{DC}

AC ELECTRICAL CHARACTERISTICS

Min and Max limits apply for $4.5 \le V_{CC} \le 5.5 V$.

Typical data apply at $T_A = 25^{\circ}C$ and $V_{CC} = +5V$.

SYMBOL	DADAMETED	TEST CONDITIONS	SA5225		UNIT	
STMBOL	YMBOL PARAMETER TEST CONDITIONS	Min	Тур	Max		
BW ₁	Lower –3dB bandwidth	$C_{AZ} = 0.1 \mu F$	0.5	1.0	1.5	kHz
BW ₂	Upper –3dB bandwidth		90	120	150	MHz
R _{IN}	Input resistance	Pin 4 or 5	2.9	4.5	7.6	kΩ
C _{IN}	Input capacitance	Pin 4 or 5			2.5	pF
t _r , t _f	ECL output ¹ risetime, falltime	$R_{L} = 50\Omega$ To V _{CCE} - 2V 20-80%	1.2		2.2	ns
t _{PWD}	Pulsewidth distortion				0.3	ns _{P-P}
R _{AZ}	Auto zero output resistance	Pin 1 or 2	155	250	423	kΩ
R _F	Level-detect filter resistance	Pin 7	14	24	41	kΩ
t _{LD}	Level-detect time constant	C _F = 0	0.5	1.0	2.0	μs

NOTE:

1. Both outputs should be terminated identically to minimize differential feedback to the device inputs on a PC board or substrate.

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Fiber optic postamplifier

Figure 3. Typical Fiber Optic Receiving System

INPUT BIASING

The DATA INPUT pins (4 and 5) are DC biased at approximately 2.9V by an internal reference generator. The SA5225 can be DC coupled, but the driving source must operate within the allowable 1.4V to 4.4V input signal range (for $V_{CC} = 5V$). If AC coupling is used to remove any DC compatibility requirement, the coupling capacitors C1 and C2 must be large enough to pass the lowest input frequency of interest. For example, .001µF coupling capacitors react with the internal 4.5k input bias resistors to yield a lower –3dB frequency of 35kHz. This then sets a limit on the maximum number of consecutive "1"s or "0"s that can be sensed accurately at the system data rate. Capacitor tolerance and resistor variation (2.9k to 7.6k) must be included for an accurate calculation.

AUTO-ZERO CIRCUIT

Figure 5 also shows the essential details of the auto-zero circuit. A feedback amplifier (A4) is used to cancel the offset voltage of the forward signal path, so the input to the internal ECL comparator (A6) is at its toggle point in the absence of any input signal. The time constant of the cancelling circuitry is set by an external capacitor (C_{AZ}) connected between Pins 1 and 2. The formula for the lower –3dB frequency is:

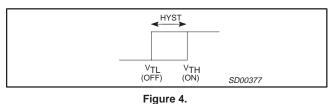
$$f_{-3dB} = \frac{150}{2\pi \cdot R_{AZ} \cdot C_{AZ}}$$

where R_{AZ} is the internal driving impedance which can vary from 155k to 423k over temperature and device fabrication limits. The input coupling time constant must also be considered in determining the lower frequency response of the SA5225.

INPUT SIGNAL LEVEL-DETECTION

The SA5225 allows for user programmable input signal level-detection and can automatically disable the switching of its ECL data outputs if the input is below a set threshold. This prevents the outputs from reacting to noise in the absence of a valid input signal, and insures that data will only be transmitted when the input signal-to-noise ratio is sufficient for low bit-error-rate system operation. Complimentary ECL flags (ST and STB) indicate whether the input signal is above or below the desired threshold level.

Figure 6 shows a simplified block diagram of the SA5225 level-detect system. The input signal is amplified and rectified before being compared to a programmable reference. A filter is included to prevent noise spikes from triggering the level-detector. This filter has a nominal 1 μ s time constant, and additional filtering can be achieved by using an external capacitor (CF) from Pin 7 to V_{CCA} (the internal driving impedance is nominally 24k). The resultant signal is then compared to a programmable level, V_{SET}, which is set by an internal voltage reference (2.64V) and an external resistor divider (R1 and R2). The value of R1 + R2 should be maintained at approximately 5k.



The circuit is designed to operate accurately over a differential 2-12mV_{P-P} square-wave input level detect range. This level, $V_{\text{SET}}/100$, is the average of V_{TH} and V_{TL} .

Nominal hysteresis of 3dB is provided by the complimentary ECL output comparator yielding $V_{TL} = \frac{V_{SET}}{121}$ and $V_{TH} = \frac{V_{SET}}{85}$. For example, with $V_{SET} = 1.2V$, a 14.05mV_{P-P} square-wave differential input will drive the ST pin high, and an input level below 9.95mV_{P-P} will drive the ST pin low.

Since a "JAM" function is provided (Pin 8) and can force the data outputs to a predetermined state ($D_{OUT} = LOW$, $\overline{D_{OUT}} = HIGH$), the ST and JAM pins can be connected together to automatically disable signal transmission when the chip senses that the input signal is below the desired threshold. JAM (Pin 8) low enables the Data Outputs. ST will be in a high ECL state for input signals below threshold.

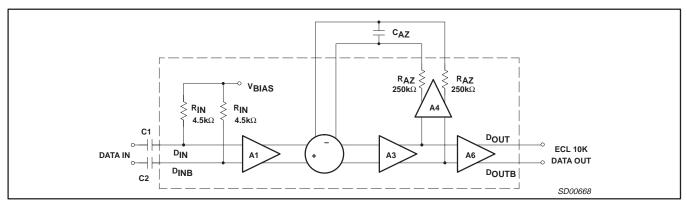


Figure 5. SA5225 Sample Application: Forward Gain Path Including Auto-Zero

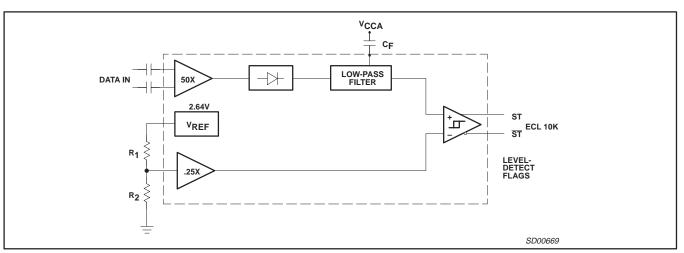


Figure 6. SA5225 Sample Application: Input Signal Level-Detect System

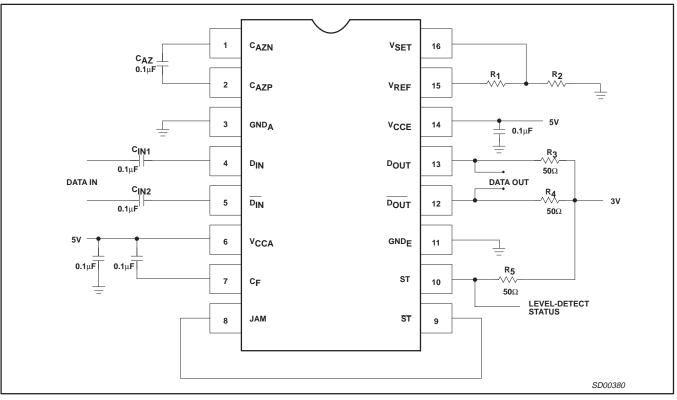


Figure 7. SA5225 Sample Application with $V_{CC} = 5.0V$

NOTE: A 50 Ω resistor is required from Pin 9 to 3V only if the \overline{ST} pin is required to meet 10k ECL specifications.

Die Sales Disclaimer

Due to the limitations in testing high frequency and other parameters at the die level, and the fact that die electrical characteristics may shift after packaging, die electrical parameters are not specified and die are not guaranteed to meet electrical characteristics (including temperature range) as noted in this data sheet which is intended only to specify electrical characteristics for a packaged device. All die are 100% functional with various parametrics tested at the wafer level, at room temperature only (25°C), and are guaranteed to be 100% functional as a result of electrical testing to the point of wafer sawing only. Although the most modern processes are utilized for wafer sawing and die pick and place into waffle pack carriers, it is impossible to guarantee 100% functionality through this process. There is no post waffle pack testing performed on individual die.

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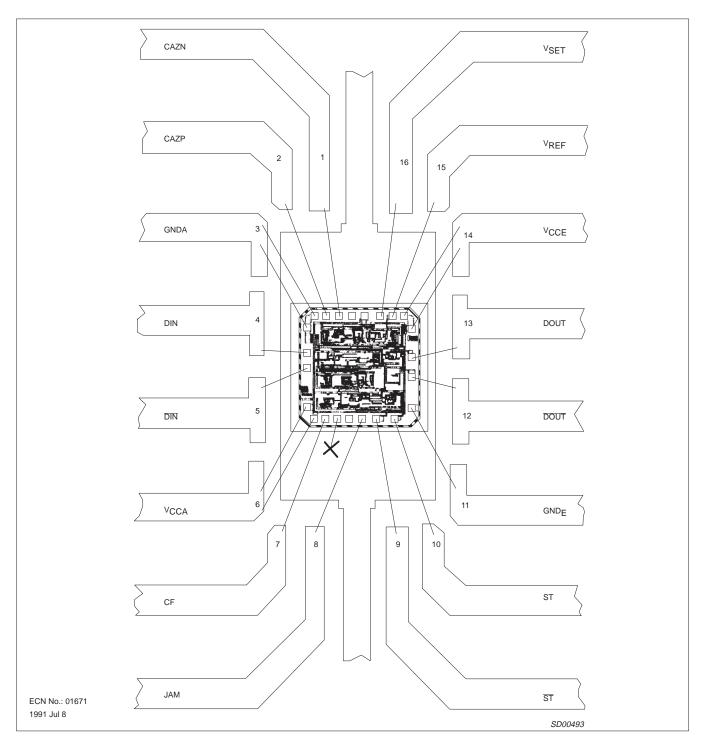
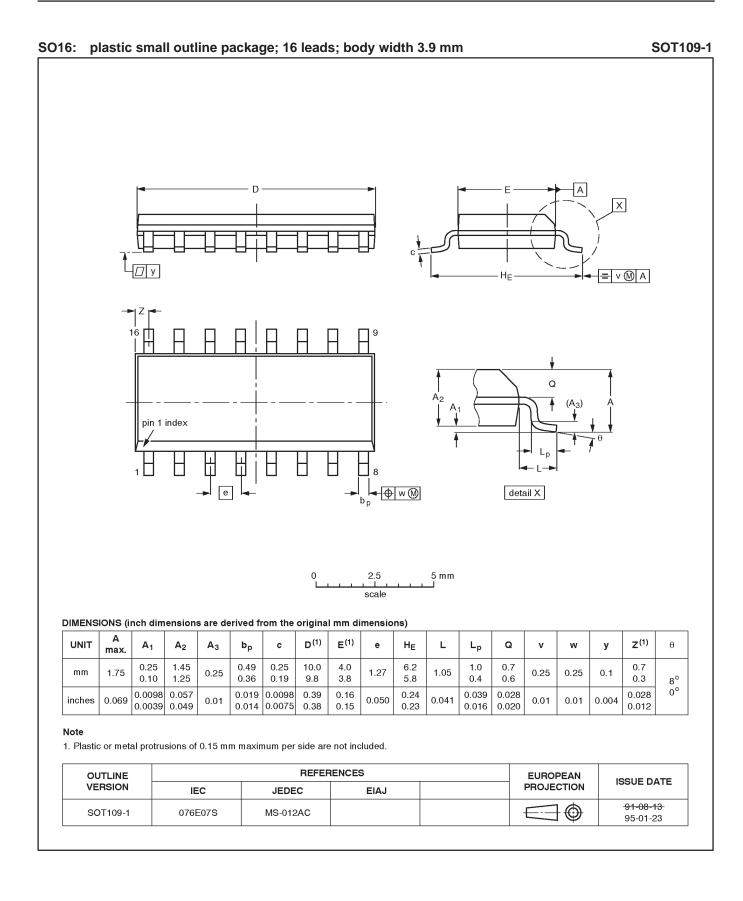


Figure 8. SA5225 Bonding Diagram

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Product specification



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NOTES

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Data sheet status

Data sheet status	Product status	Definition ^[1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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